

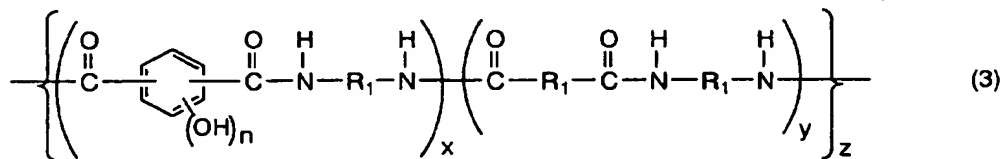
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English translation of Amendment Under Article 34
Replacement Pages 32 and 33

CLAIMS

1. A process for producing a surface-adhesive film comprising applying a polyimide precursor solution to a substrate, drying the polyimide precursor solution to prepare a polyimide precursor film, applying an adhesive aid composition containing a phenolic hydroxyl group-containing polyamide and a solvent to the polyimide precursor film, drying the adhesive aid composition, and then imidizing the polyimide precursor by heating at 200°C to 500°C.

2. The process for producing a surface-adhesive film according to claim 1, wherein the phenolic hydroxyl group-containing polyamide is a polyamide having a repeat structure represented by formula (3):



(wherein R₁ represents a divalent aromatic group and R₁s in repeating units may be the same or different; n represents an average number of substituents and is a positive number of 1 to 4; and x, y, and z represent average degrees of polymerization and are positive numbers of 1 to 10, 0 to 20, and 1 to 50, respectively).

3. The process for producing a surface-adhesive film

according to claim 1 or 2, the process comprising applying a polyimide precursor solution to a substrate, drying the precursor solution at 50°C to 150°C for 5 to 180 minutes to prepare a polyimide precursor film, applying an adhesive aid composition containing a phenolic hydroxyl group-containing polyamide and a solvent to the polyimide precursor film, drying the composition at 50°C to 150°C for 5 to 180 minutes, and then imidizing the polyimide precursor at 200°C to 500°C for 20 to 300 minutes under a nitrogen stream.

4. A film produced by the process according to any one of claims 1 to 3.

5. A single-sided copper-clad laminate comprising the film according to claim 4.

6. A double-sided copper-clad laminate comprising the film according to claim 4.

7. A flexible printed wiring board comprising the film according to claim 4.

8. A multilayer printed wiring board comprising the film according to claim 4.